



**Certificate Concerning Xilinx Programmable Logic Devices  
Designated as RoHS Compliant  
(‘6 of 6’ Disclosure)**

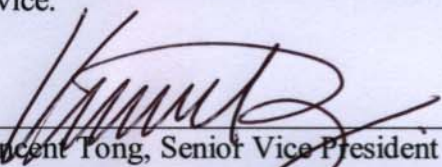
Xilinx, Inc. certifies that to the best of its knowledge programmable logic devices designated by Xilinx to be RoHS Compliant conform to requirements of 2002/95/EC, the European Union Restriction on the Use of Hazardous Substances (RoHS) Directive.

Xilinx defines the terms ‘RoHS Compliant’, ‘lead free’ and ‘green’ to be synonymous and indicate that the named products are compliant with the current EU RoHS Directive maximum concentration values for all six (6) identified substances within the Directive – specifically Cadmium, Lead, Mercury, Hexavalent Chromium, Polybrominated Biphenyl and Polybrominated Diphenyl Ether (including Decabromodiphenyl Ether, or DecaBDE) as indicated in the table below.

This includes Xilinx’ RoHS Compliant IC Flip Chip BGA packages that contain small amounts of lead, located in the solder bump, and are compliant by exemption, “*lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated Flip Chip packages*” (Directive 2002/95/EC).

<b>Banned Substance</b>	<b>Maximum Concentration Values (ppm)</b>
Cadmium	100
Lead	1000
Mercury	1000
Hexavalent Chromium	1000
Polybrominated Biphenyl (PBB)	1000
Polybrominated Diphenyl Ether (PBDE)	1000

RoHS Complaint products are specified by adding a ‘G’ character to the package designator portion of the standard part number. For example, XC2S100E-6TQ144C would be XC2S100E-6TQG144C for the RoHS Compliant version. Parts ordered using this nomenclature are marked as such on the actual device.

  
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Vincent Tong, Senior Vice President  
Worldwide Quality & New Product Introductions

*5/28/2008*  
Date

**Important Information and Disclaimer:** The statements made herein are based on understanding by Xilinx of the RoHS Directive and its knowledge of the materials used in the manufacture of its products as of the date of such statements. Information provided by Xilinx on its website or in other company communications concerning the content of its products represents the knowledge and belief of Xilinx as of the date that it is provided. All statements are contingent upon the accuracy of such information. Xilinx continues to take steps to provide accurate information but, in some cases, may not conduct destructive testing or chemical analysis on incoming materials and chemicals.